

In re: M. Koike
Filed: concurrently
USSN: not assigned
For: Semiconductor Device, Resin Sealing Method and Resin Sealing Device

IN THE U.S. PATENT AND TRADEMARK

In re Application of:
M. KOIKE

Serial No.: not assigned

Examiner: not assigned

Filed: Concurrently

Art Unit: not assigned

For: Semiconductor Device, Resin Sealing Method and Resin Sealing Device

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents
Washington, DC 20231

Sir:

Please calculate the filing fee based on the Preliminary Amendment.

Prior to Examination, please amend the above-identified application as follows:

In the Claims:

Please amend the claims as follows:

4. (Amended) A semiconductor device as set forth in claim 1 [or 2], wherein said molded resin portion is formed with an over-hang portion overlapping with the upper end surface of said semiconductor device.

5. (Amended) A semiconductor device as set forth in claim 1 [or 2], wherein said molded resin portion is formed over substantially entire area of said wired substrate.

6. (Amended) A semiconductor device as set forth in claim 1 [or 2], wherein said resin is injected through one or more through holes provided in said wired substrate for electrical connection under pressure for forming said under-fill region and said molded resin portion.